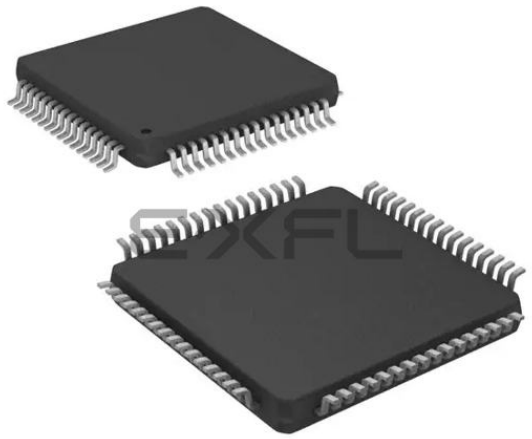

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Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	192KB (65.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj192ga106-e-pt

TABLE 4-27: SYSTEM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	—	—	CM	PMSLP	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	**Note 1**
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	IOLOCK	LOCK	—	CF	POSCEN	SOSCEN	OSWEN	**Note 2**
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	RCDIV2	RCDIV1	RCDIV0	—	—	—	—	—	—	—	—	0100
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0	0000
REFOCON	074E	ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The Reset value of the RCON register is dependent on the type of Reset event. See **Section 6.0 "Resets"** for more information.

2: The Reset value of the OSCCON register is dependent on both the type of Reset event and the device configuration. See **Section 8.0 "Oscillator Configuration"** for more information.

TABLE 4-28: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	—	—	—	—	—	—	ERASE	—	—	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000(1)
NVMKEY	0766	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-29: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	ADC1MD	0000
PMD2	0772	IC8MD	IC7MD	IC6MD	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	OC8MD	OC7MD	OC6MD	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0774	—	—	—	—	—	CMPMD	RTCCMD	PMPMD	CRCMD	—	—	—	U3MD	I2C3MD	I2C2MD	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	U4MD	—	REFOMD	CTMUMD	LVDMD	—	0000
PMD5	0778	—	—	—	—	—	—	—	IC9MD	—	—	—	—	—	—	—	OC9MD	0000
PMD6	077A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SPI3MD	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
ALTIVT	DISI	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ALTIVT:** Enable Alternate Interrupt Vector Table bit
1 = Use Alternate Interrupt Vector Table
0 = Use standard (default) vector table

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13-5 **Unimplemented:** Read as ‘0’

bit 4 **INT4EP:** External Interrupt 4 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 3 **INT3EP:** External Interrupt 3 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

REGISTER 7-35: IPC20: INTERRUPT PRIORITY CONTROL REGISTER 20

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U3TXIP2	U3TXIP1	U3TXIP0	—	U3RXIP2	U3RXIP1	U3RXIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	U3ERIP2	U3ERIP1	U3ERIP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U3TXIP<2:0>:** UART3 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **U3RXIP<2:0>:** UART3 Receiver Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **U3ERIP<2:0>:** UART3 Error Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

REGISTER 7-37: IPC22: INTERRUPT PRIORITY CONTROL REGISTER 22

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI3IP2	SPI3IP1	SPI3IP0	—	SPF3IP2	SPF3IP1	SPF3IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U4TXIP2	U4TXIP1	U4TXIP0	—	U4RXIP2	U4RXIP1	U4RXIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **SPI3IP<2:0>:** SPI3 Event Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **SPF3IP<2:0>:** SPI3 Fault Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **U4TXIP<2:0>:** UART4 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U4RXIP<2:0>:** UART4 Receiver Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

10.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORT, LAT and TRIS registers for data control, each port pin can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs higher than V_{DD} (e.g., 5V) on any desired digital only pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

10.2 Configuring Analog Port Pins

The AD1PCFGL and TRIS registers control the operation of the A/D port pins. Setting a port pin as an analog input also requires that the corresponding TRIS bit be set. If the TRIS bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level).

Pins configured as digital inputs will not convert an analog input. Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

10.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a `NOP`.

10.2.2 ANALOG INPUT PINS AND VOLTAGE CONSIDERATIONS

The voltage tolerance of pins used as device inputs is dependent on the pin's input function. Pins that are used as digital only inputs are able to handle DC voltages up to 5.5V, a level typical for digital logic circuits. In contrast, pins that also have analog input functions of any kind can only tolerate voltages up to V_{DD}. Voltage excursions beyond V_{DD} on these pins are always to be avoided. Table 10-1 summarizes the input capabilities. Refer to **Section 28.1 "DC Characteristics"** for more details.

> **Note:** For easy identification, the pin diagrams at the beginning of this data sheet also indicate 5.5V tolerant pins with dark grey shading.

TABLE 10-1: INPUT VOLTAGE LEVELS(1)

Port or Pin	Tolerated Input	Description
PORTA<10:9>	V_{DD}	Only V_{DD} input levels tolerated.
PORTB<15:0>		
PORTC<15:12>		
PORTD<7:6>		
PORTF<0>		
PORTG<9:6>		
PORTA<15:14>, PORTA<7:0>	5.5V	Tolerates input levels above V_{DD}, useful for most standard logic.
PORTC<4:1>		
PORTD<15:8>, PORTD<5:0>		
PORTE<9:0>		
PORTF<13:12>, PORTF<8:1>		
PORTG<15:12>, PORTG<3:0>		

Note 1: Not all port pins shown here are implemented on 64-pin and 80-pin devices. Refer to **Section 1.0 "Device Overview"** to confirm which ports are available in specific devices.

EXAMPLE 10-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0          ; Configure PORTB<15:8> as inputs
MOV   W0, TRISB           ; and PORTB<7:0> as outputs
NOP                       ; Delay 1 cycle
BTSS  PORTB, #13          ; Next Instruction
```

REGISTER 10-32: RPOR10: PERIPHERAL PIN SELECT OUTPUT REGISTER 10

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP21R5	RP21R4	RP21R3	RP21R2	RP21R1	RP21R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP20R5	RP20R4	RP20R3	RP20R2	RP20R1	RP20R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP21R<5:0>:** RP21 Output Pin Mapping bits
Peripheral output number n is assigned to pin, RP21 (see Table 10-3 for peripheral function numbers).

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP20R<5:0:>** RP20 Output Pin Mapping bits
Peripheral output number n is assigned to pin, RP20 (see Table 10-3 for peripheral function numbers).

REGISTER 10-33: RPOR11: PERIPHERAL PIN SELECT OUTPUT REGISTER 11

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP23R5	RP23R4	RP23R3	RP23R2	RP23R1	RP23R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP22R5	RP22R4	RP22R3	RP22R2	RP22R1	RP22R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP23R<5:0>:** RP23 Output Pin Mapping bits
Peripheral output number n is assigned to pin, RP23 (see Table 10-3 for peripheral function numbers).

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP22R<5:0>:** RP22 Output Pin Mapping bits
Peripheral output number n is assigned to pin, RP22 (see Table 10-3 for peripheral function numbers).

REGISTER 13-1: ICxCON1: INPUT CAPTURE x CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R-0, HCS	R-0, HCS	R/W-0	R/W-0	R/W-0
—	ICI1	ICI0	ICOV	ICBNE	ICM2(1)	ICM1(1)	ICM0(1)
bit 7							bit 0

Legend:	HCS = Hardware Clearable/Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ICSIDL:** Input Capture x Module Stop in Idle Control bit
1 = Input capture module halts in CPU Idle mode
0 = Input capture module continues to operate in CPU Idle mode

bit 12-10 **ICTSEL<2:0>:** Input Capture Timer Select bits
111 = System clock (FOSC/2)
110 = Reserved
101 = Reserved
100 = Timer1
011 = Timer5
010 = Timer4
001 = Timer2
000 = Timer3

bit 9-7 **Unimplemented:** Read as '0'

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

bit 4 **ICOV:** Input Capture x Overflow Status Flag bit (read-only)
1 = Input capture overflow occurred
0 = No input capture overflow occurred

bit 3 **ICBNE:** Input Capture x Buffer Empty Status bit (read-only)
1 = Input capture buffer is not empty, at least one more capture value can be read
0 = Input capture buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits(1)
111 = Interrupt mode: Input capture functions as interrupt pin only when device is in Sleep or Idle mode (rising edge detect only, all other control bits are not applicable)
110 = Unused (module disabled)
101 = Prescaler Capture mode: Capture on every 16th rising edge
100 = Prescaler Capture mode: Capture on every 4th rising edge
011 = Simple Capture mode: Capture on every rising edge
010 = Simple Capture mode: Capture on every falling edge
001 = Edge Detect Capture mode: Capture on every edge (rising and falling), ICI<1:0> bits do not control interrupt generation for this mode
000 = Input capture module turned off

Note 1: The ICx input must also be configured to an available RPn pin. For more information, see **Section 10.4 "Peripheral Pin Select"**.

REGISTER 21-7: AD1CSSL: A/D INPUT SCAN SELECT REGISTER (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSSL15	CSSL14	CSSL13	CSSL12	CSSL11	CSSL10	CSSL9	CSSL8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **CSSL<15:0>:** A/D Input Pin Scan Selection bits
`1` = Corresponding analog channel selected for input scan
`0` = Analog channel omitted from input scan

25.0 SPECIAL FEATURES

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the following sections of the *"PIC24F Family Reference Manual"*: • **Section 9. "Watchdog Timer (WDT)"** (DS39697) • **Section 32. "High-Level Device Integration"** (DS39719) • **Section 33. "Programming and Diagnostics"** (DS39716)

PIC24FJ256GA110 family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming
- In-Circuit Emulation

25.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped starting at program memory location F80000h. A detailed explanation of the various bit functions is provided in Register 25-1 through Register 25-5.

Note that address F80000h is beyond the user program memory space. In fact, it belongs to the configuration memory space (800000h-FFFFFFh) which can only be accessed using table reads and table writes.

25.1.1 CONSIDERATIONS FOR CONFIGURING PIC24FJ256GA110 FAMILY DEVICES

In PIC24FJ256GA110 family devices, the configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the three words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 25-1. These are packed representations of the actual device Configuration bits, whose actual locations are distributed among several locations in configuration space. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

Note:	Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Word for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The upper byte of all Flash Configuration Words in program memory should always be '1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note:	Performing a page erase operation on the last page of program memory clears the Flash Configuration Words, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

TABLE 25-1: FLASH CONFIGURATION WORD LOCATIONS FOR PIC24FJ256GA110 FAMILY DEVICES

Device	Configuration Word Addresses		
	1	2	3
PIC24FJ64GA1	ABFEh	ABFCh	ABFAh
PIC24FJ128GA1	157FEh	157FC	157FA
PIC24FJ192GA1	20BFEh	20BFC	20BFA
PIC24FJ256GA1	2ABFEh	2ABFC	2ABFA

25.2.2 ON-CHIP REGULATOR AND POR

When the voltage regulator is enabled, it takes approximately 10 µs for it to generate output. During this time, designated as T_{VREG}, code execution is disabled. T_{VREG} is applied every time the device resumes operation after any power-down, including Sleep mode. The length of T_{VREG} is determined by the PMSLP bit (RCON<8>), as described in **Section 25.2.5 “Voltage Regulator Standby Mode”**.

If the regulator is disabled, a separate Power-up Timer (PWRT) is automatically enabled. The PWRT adds a fixed delay of 64 ms nominal delay at device start-up (POR or BOR only). When waking up from Sleep with the regulator disabled, the PMSLP bit determines the wake-up time. When operating with the regulator disabled, setting PMSLP can decrease the device wake-up time.

25.2.3 ON-CHIP REGULATOR AND BOR

When the on-chip regulator is enabled, PIC24FJ256GA110 family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain the tracking level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage specifications are provided in the *“PIC24FJ Family Reference Manual”*, **Section 7. “Reset”** (DS39712).

25.2.4 POWER-UP REQUIREMENTS

The on-chip regulator is designed to meet the power-up requirements for the device. If the application does not use the regulator, then strict power-up conditions must be adhered to. While powering up, V_{DDCORE} must never exceed V_{DD} by 0.3 volts.

Note:	For more information, see **Section 28.0 “Electrical Characteristics”**.

25.2.5 VOLTAGE REGULATOR STANDBY MODE

When enabled, the on-chip regulator always consumes a small incremental amount of current over I_{DD}/I_{PD}, including when the device is in Sleep mode, even though the core digital logic does not require power. To provide additional savings in applications where power resources are critical, the regulator automatically disables itself whenever the device goes into Sleep mode. This feature is controlled by the PMSLP bit (RCON<8>). By default, the bit is cleared, which removes power from the Flash program memory, and thus, enables Standby mode. When waking up from Standby mode, the regulator must wait for T_{VREG} to expire before wake-up. This extra time is needed to ensure that the regulator can source enough current to power the Flash memory.

For applications which require a faster wake-up time, it is possible to disable regulator Standby mode. The PMSLP bit can be set to turn off Standby mode so that the Flash stays powered when in Sleep mode and the device can wake-up without waiting for T_{VREG}. When PMSLP is set, the power consumption while in Sleep mode, will be approximately 40 µA higher than power consumption when the regulator is allowed to enter Standby mode.

25.3 Watchdog Timer (WDT)

For PIC24FJ256GA110 family devices, the WDT is driven by the LPRC Oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 31 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the FWPSA Configuration bit. With a 31 kHz input, the prescaler yields a nominal WDT time-out period (T_{WDT}) of 1 ms in 5-bit mode or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPS<3:0> Configuration bits (CW1<3:0>), which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a `PWRSAV` instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a `CLRWDT` instruction during normal execution

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the `PWRSAV` instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3:2>) will need to be cleared in software after the device wakes up.

The WDT Flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note:	The `CLRWDT` and `PWRSAV` instructions clear the prescaler and postscaler counts when executed.

TABLE 26-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
GOTO	GOTO Expr	Go to Address	2	2	None
	GOTO Wn	Go to Indirect	1	2	None
INC	INC f	f = f + 1	1	1	C, DC, N, OV, Z
	INC f,WREG	WREG = f + 1	1	1	C, DC, N, OV, Z
	INC Ws,Wd	Wd = Ws + 1	1	1	C, DC, N, OV, Z
INC2	INC2 f	f = f + 2	1	1	C, DC, N, OV, Z
	INC2 f,WREG	WREG = f + 2	1	1	C, DC, N, OV, Z
	INC2 Ws,Wd	Wd = Ws + 2	1	1	C, DC, N, OV, Z
IOR	IOR f	f = f .IOR. WREG	1	1	N, Z
	IOR f,WREG	WREG = f .IOR. WREG	1	1	N, Z
	IOR #lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N, Z
	IOR Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N, Z
	IOR Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N, Z
LNK	LNK #lit14	Link Frame Pointer	1	1	None
LSR	LSR f	f = Logical Right Shift f	1	1	C, N, OV, Z
	LSR f,WREG	WREG = Logical Right Shift f	1	1	C, N, OV, Z
	LSR Ws,Wd	Wd = Logical Right Shift Ws	1	1	C, N, OV, Z
	LSR Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N, Z
	LSR Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N, Z
MOV	MOV f,Wn	Move f to Wn	1	1	None
	MOV [Wns+Slit10],Wnd	Move [Wns+Slit10] to Wnd	1	1	None
	MOV f	Move f to f	1	1	N, Z
	MOV f,WREG	Move f to WREG	1	1	N, Z
	MOV #lit16,Wn	Move 16-bit Literal to Wn	1	1	None
	MOV.b #lit8,Wn	Move 8-bit Literal to Wn	1	1	None
	MOV Wn,f	Move Wn to f	1	1	None
	MOV Wns,[Wns+Slit10]	Move Wns to [Wns+Slit10]	1	1	
	MOV Wso,Wdo	Move Ws to Wd	1	1	None
	MOV WREG,f	Move WREG to f	1	1	N, Z
	MOV.D Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
	MOV.D Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
MUL	MUL.SS Wb,Ws,Wnd	{Wnd + 1, Wnd} = Signed(Wb) * Signed(Ws)	1	1	None
	MUL.SU Wb,Ws,Wnd	{Wnd + 1, Wnd} = Signed(Wb) * Unsigned(Ws)	1	1	None
	MUL.US Wb,Ws,Wnd	{Wnd + 1, Wnd} = Unsigned(Wb) * Signed(Ws)	1	1	None
	MUL.UU Wb,Ws,Wnd	{Wnd + 1, Wnd} = Unsigned(Wb) * Unsigned(Ws)	1	1	None
	MUL.SU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = Signed(Wb) * Unsigned(lit5)	1	1	None
	MUL.UU Wb,#lit5,Wnd	{Wnd + 1, Wnd} = Unsigned(Wb) * Unsigned(lit5)	1	1	None
	MUL f	W3:W2 = f * WREG	1	1	None
NEG	NEG f	f = $\overline{f}$ + 1	1	1	C, DC, N, OV, Z
	NEG f,WREG	WREG = $\overline{f}$ + 1	1	1	C, DC, N, OV, Z
	NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C, DC, N, OV, Z
NOP	NOP	No Operation	1	1	None
	NOPR	No Operation	1	1	None
POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
	POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
	POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
	POP.S	Pop Shadow Registers	1	1	All
PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
	PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
	PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
	PUSH.S	Push Shadow Registers	1	1	None

TABLE 28-5: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current, PMD Bits are Set(2)						
DC40	220	310	μA	-40°C	2.0V(3)	1 MIPS
DC40a	220	310	μA	+25°C		
DC40b	220	310	μA	+85°C		
DC40c	260	350	μA	+125°C		
DC40d	300	390	μA	-40°C	3.3V(4)	
DC40e	300	390	μA	+25°C		
DC40f	320	420	μA	+85°C		
DC40g	340	450	μA	+125°C		
DC43	0.85	1.1	mA	-40°C	2.0V(3)	4 MIPS
DC43a	0.85	1.1	mA	+25°C		
DC43b	0.87	1.2	mA	+85°C		
DC43c	0.87	1.2	mA	+125°C		
DC43d	1.1	1.4	mA	-40°C	3.3V(4)	
DC43e	1.1	1.4	mA	+25°C		
DC43f	1.1	1.4	mA	+85°C		
DC43g	1.1	1.5	mA	+125°C		
DC47	4.4	5.6	mA	-40°C	2.5V(3)	16 MIPS
DC47a	4.4	5.6	mA	+25°C		
DC47b	4.4	5.6	mA	+85°C		
DC47c	4.4	5.6	mA	+125°C		
DC47d	4.4	5.6	mA	-40°C	3.3V(4)	
DC47e	4.4	5.6	mA	+25°C		
DC47f	4.4	5.6	mA	+85°C		
DC47g	4.4	5.6	mA	+125°C		
DC50	1.1	1.4	mA	-40°C	2.0V(3)	FRC (4 MIPS)
DC50a	1.1	1.4	mA	+25°C		
DC50b	1.1	1.4	mA	+85°C		
DC50c	1.2	1.5	mA	+125°C		
DC50d	1.4	1.8	mA	-40°C	3.3V(4)	
DC50e	1.4	1.8	mA	+25°C		
DC50f	1.4	1.8	mA	+85°C		
DC50g	1.4	1.8	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IIDLE current is measured with core off, clock on, all modules off and all of the Peripheral Module Disable (PMD) bits are set.

3: On-chip voltage regulator disabled (ENVREG tied to VSS).

4: On-chip voltage regulator enabled (ENVREG tied to VDD).

TABLE 28-7: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ[1]**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage[4]**					
DI10		I/O Pins with ST Buffer	VSS	—	0.2 VDD	V	
DI11		I/O Pins with TTL Buffer	VSS	—	0.15 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		OSC1 (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSC1 (HS mode)	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I²C™ Buffer	VSS	—	0.3 VDD	V	
DI19		I/O Pins with SMBus Buffer	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage[4,5]**					
DI20		I/O Pins with ST Buffer: with Analog Functions Digital Only	 0.8 VDD 0.8 VDD	 — —	 VDD 5.5	 V V	
DI21		I/O Pins with TTL buffer: with Analog Functions Digital Only	 0.25 VDD + 0.8 0.25 VDD + 0.8	 — —	 VDD 5.5	 V V	
DI25		$\overline{\text{MCLR}}$	0.8 VDD	—	VDD	V	
DI26		OSC1 (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSC1 (HS mode)	0.7 VDD	—	VDD	V	
DI28		I/O Pins with I²C Buffer: with Analog Functions Digital Only	 0.7 VDD 0.7 VDD	 — —	 VDD 5.5	 V V	
DI29		I/O Pins with SMBus Buffer: with Analog Functions Digital Only	 2.1 2.1		 VDD 5.5	 V V	2.5V ≤ VPIN ≤ VDD
DI30	ICNPU	**CNx Pull-up Current**	50	250	400	μA	VDD = 3.3V, VPIN = 0
DI30A	ICNPD	**CNx Pull-Down Current**	—	80	—	μA	VDD = 3.3V, VPIN = VDD
DI31	IPU	**Maximum Load Current** for Digital High Detection w/ Internal Pull-up	— —	— —	30 100	μA μA	VDD = 2.0V VDD = 3.3V

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-4 for I/O pins buffer types.

5: VIH requirements are met when internal pull-ups are enabled.

TABLE 28-14: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 2.0V TO 3.6V)

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	Sym	Characteristic[1]	Min	Typ[2]	Max	Units	Conditions
OS50	F_{PLLI}	PLL Input Frequency Range[2]	4	—	8	MHz	ECPLL, HSPLL, XTPLL modes
OS51	F_{SYS}	PLL Output Frequency Range	16	—	32	MHz	
OS52	T_{LOCK}	PLL Start-up Time (Lock Time)	—	—	2	ms	
OS53	D_{CLK}	CLKO Stability (Jitter)	-2	1	+2	%	

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 28-15: INTERNAL RC OSCILLATOR SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions
	T_{FRC}	FRC Start-up Time	—	15	—	μs	
	T_{LPRC}	LPRC Start-up Time	—	40	—	μs	

TABLE 28-16: INTERNAL RC OSCILLATOR ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	Characteristic	Min	Typ	Max	Units	Conditions
F20	FRC Accuracy @ 8 MHz[1]	-2	—	2	%	+25°C, 3.0V ≤ V_{DD} ≤ 3.6V
		-5	—	5	%	-40°C ≤ T_A ≤ +85°C, 3.0V ≤ V_{DD} ≤ 3.6V
F21	LPRC Accuracy @ 31 kHz[2]	-20	—	20	%	-40°C ≤ T_A ≤ +85°C, 3.0V ≤ V_{DD} ≤ 3.6V

Note 1: Frequency calibrated at 25°C and 3.3V. OSCTUN bits can be used to compensate for temperature drift.
2: Change of LPRC frequency as V_{DD} changes.

FIGURE 28-12: SPIx MODULE MASTER MODE TIMING CHARACTERISTICS (CKE = 1)

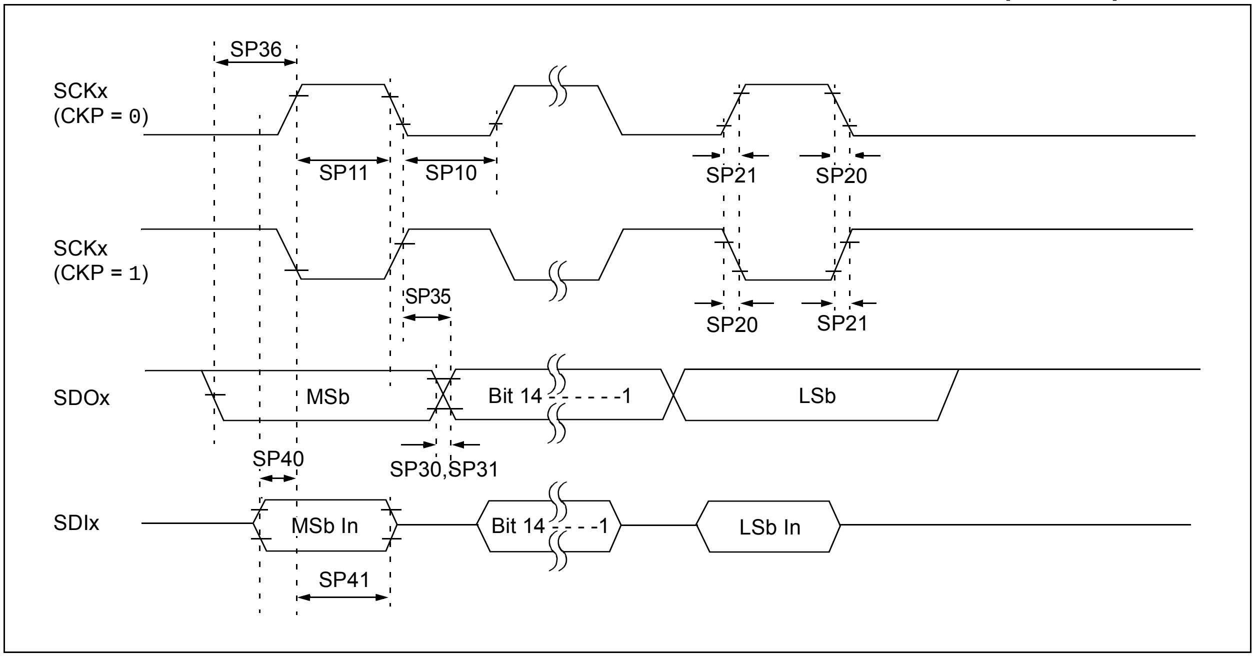


TABLE 28-25: SPIx MODULE MASTER MODE TIMING REQUIREMENTS (CKE = 1)

AC CHARACTERISTICS			**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time(2)	TCY/2	—	—	ns	
SP11	TscH	SCKx Output High Time(2)	TCY/2	—	—	ns	
SP20	TscF	SCKx Output Fall Time(3)	—	10	25	ns	
SP21	TscR	SCKx Output Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	10	25	ns	
SP31	TdoR	SDOx Data Output Rise Time(3)	—	10	25	ns	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

3: Assumes 50 pF load on all SPIx pins.

FIGURE 28-14: SPIx MODULE SLAVE MODE TIMING CHARACTERISTICS (CKE = 1)

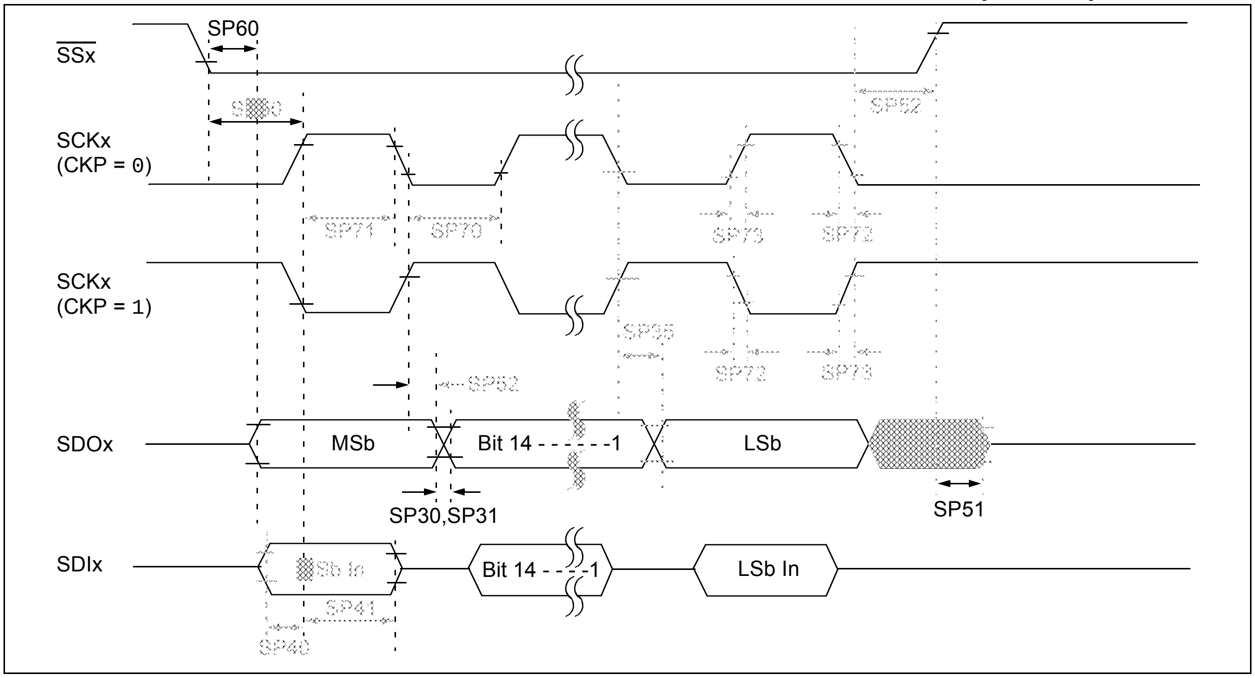


TABLE 28-27: SPIx MODULE SLAVE MODE TIMING REQUIREMENTS (CKE = 1)

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	
SP71	TscH	SCKx Input High Time	30	—	—	ns	
SP72	TscF	SCKx Input Fall Time(2)	—	10	25	ns	
SP73	TscR	SCKx Input Rise Time(2)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(2)	—	10	25	ns	
SP31	TdoR	SDOx Data Output Rise Time(2)	—	10	25	ns	
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP50	TssL2scH, TssL2scL	SSx ↓ to SCKx ↓ or SCKx ↑ Input	120	—	—	ns	
SP51	TssH2doZ	SSx ↑ to SDOx Output High-Impedance(3)	10	—	50	ns	
SP52	TscH2ssH TscL2ssH	SSx ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	
SP60	TssL2doV	SDOx Data Output Valid after SSx Edge	—	—	50	ns	

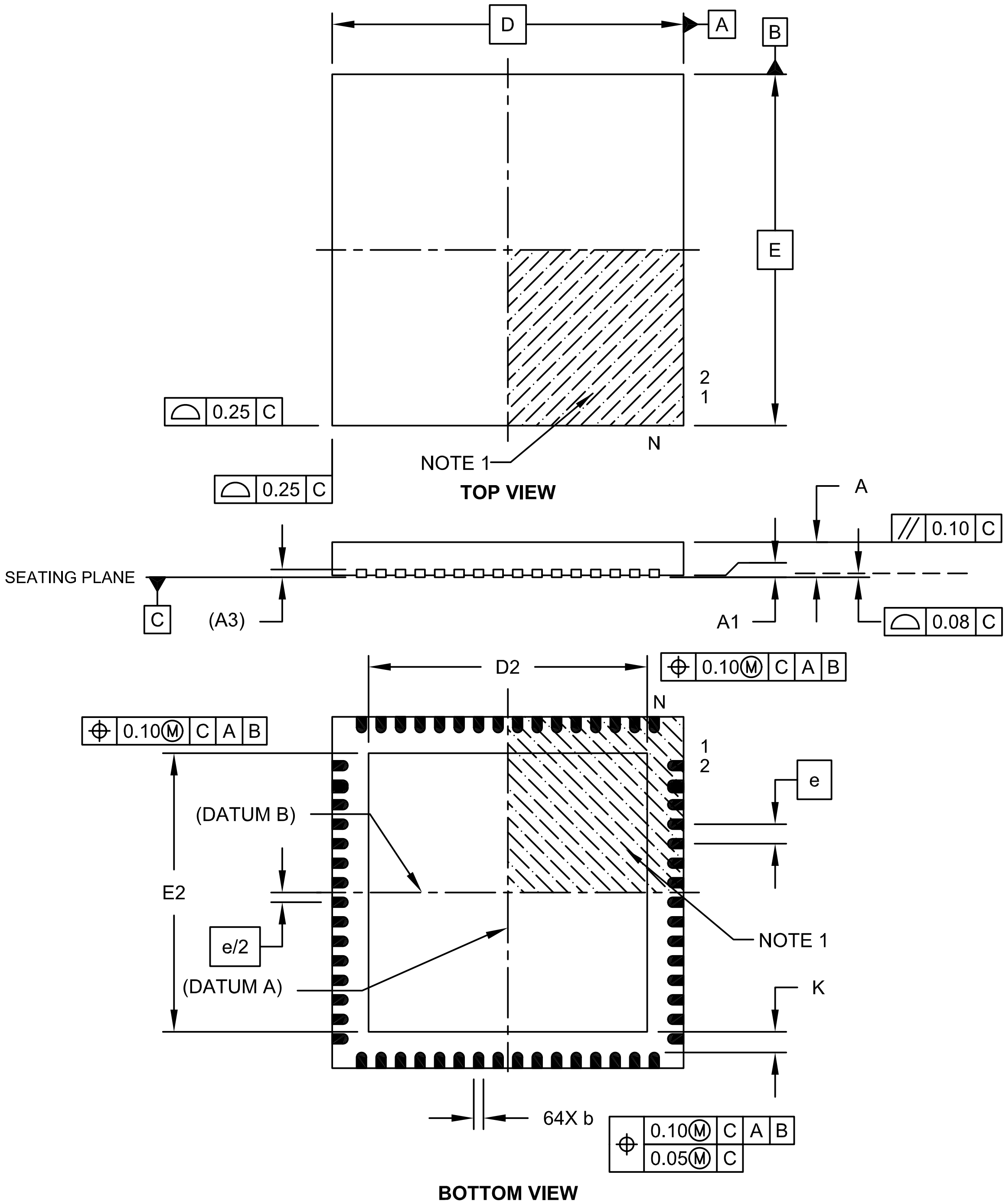
Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The minimum clock period for SCKx is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

3: Assumes 50 pF load on all SPIx pins.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-149B Sheet 1 of 2

APPENDIX A: REVISION HISTORY

Revision A (December 2007)

Original data sheet for the PIC24FJ256GA110 family of devices.

Revision B (February 2008)

Updates to **Section 28.0 “Electrical Characteristics”** and minor edits to text throughout document.

Revision C (April 2009)

Updates to all Pin Diagrams to reflect the correct order of priority for multiplexed peripherals and adds the ASCK1 pin function.

Adds packaging information for the new 64-pin QFN package to **Section 29.0 “Packaging Information”** and the Product Information System.

Updates **Section 5.0 “Flash Program Memory”** with revised code examples in assembler and new code examples in C.

Updates **Section 6.2 “Device Reset Times”** with revised information, particularly Table 6-3.

Adds the INTTREG register to **Section 4.0 “Memory Organization”** and **Section 7.0 “Interrupt Controller”**.

Makes several additions and changes to **Section 10.0 “I/O Ports”**, including:

- revision of **Section 10.4.2.1 “Peripheral Pin Select Function Priority”**
- addition of **Section 10.4.3.3 “Alternate Fixed Pin Mapping”**
- revisions to Table 10-3, “Selectable Output Sources”
- addition of the ALTRP register (and in **Section 4.0 “Memory Organization”**)

Updates **Section 15.0 “Serial Peripheral Interface (SPI)”** to include references to the ASCK1 pin function.

Updates **Section 20.0 “Programmable Cyclic Redundancy Check (CRC) Generator”** with new illustrations and a revised **Section 20.1 “User Interface”**.

Updates **Section 21.0 “10-Bit High-Speed A/D Converter”** by changing all references to AD1CHS0 to AD1CHS (as well as other locations in the document). Also revises bit field descriptions in registers: AD1CON3 (bits 7:0) and AD1CHS (bits 12:8).

Makes minor text edits to bit descriptions in **Section 22.0 “Triple Comparator Module”** (Register 22-1) and **Section 24.0 “Charge Time Measurement Unit (CTMU)”** (Register 24-1).

Updates **Section 25.2 “On-Chip Voltage Regulator”** with revised text on the operation of the regulator during POR and Standby mode.

Updates **Section 25.5 “JTAG Interface”** to remove references to programming via the interface.

Makes multiple additions and changes to **Section 28.0 “Electrical Characteristics”**, including:

- DC current characteristics for extended temperature operation (125°C)
- New DC characteristics of V_{BOR}, V_{BG}, T_{BG} and I_{CNPD}
- Addition of new V_{PEW} specification for V_{DDCORE}
- New AC characteristics for internal oscillator start-up time (T_{LPRC})
- Combination of all Internal RC Accuracy information into a single table

Makes other minor typographic corrections throughout the text.

Revision D (December 2009)

Updates **Section 2.0 “Guidelines for Getting Started with 16-bit Microcontrollers”** with the most current version.

Corrects annotations to the CN70 pin function in Table 4-4 of **Section 4.2.4 “SFR Space”**.

Corrects annotations to remappable output function 30 in Register 10-37 of **Section 10.4 “Peripheral Pin Select”**.

Corrects the definitions for the WPEND and WPFP<7:0> Configuration bits in Register 25-3 of **Section 25.1 “Configuration Bits”**.

Updates **Section 28.0 “Electrical Characteristics”** with additional data for I_{DD} at 60°C. Also corrects occurrences of “DISVREG” throughout the chapter, replacing them with “ENVREG” and the proper V_{DD}/V_{SS} connection information.

Makes other minor typographic corrections throughout the text.

Revision E (November 2010)

Updated **Section 2.0 “Guidelines for Getting Started with 16-bit Microcontrollers”** with the most current version.

Updates to **Section 28.0 “Electrical Characteristics”** with tables being added and replaced from the FRM chapters.

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